

# IC80LV51 IC80LV31



## CMOS SINGLE CHIP LOW VOLTAGE 8-BIT MICROCONTROLLER

### FEATURES

- 80C51 based architecture
- 4K x 8 ROM (IC80LV51 only)
- 128 x 8 RAM
- Two 16-bit Timer/Counters
- Full duplex serial channel
- Boolean processor
- Four 8-bit I/O ports, 32 I/O lines
- Memory addressing capability
  - 64K ROM and 64K RAM
- Programmable lock
  - Lock bits (2)
- Power save modes:
  - Idle and power-down
- Six interrupt sources
- Most instructions execute in 0.5  $\mu$ s
- CMOS and TTL compatible
- Maximum speed: 24 MHz @ Vcc = 3.3V
- Packages available:
  - 40-pin DIP
  - 44-pin PLCC
  - 44-Pin PQFP

### GENERAL DESCRIPTION

The *ICSI* IC80LV51 and IC80LV31 are high-performance microcontrollers fabricated using high-density CMOS technology. The CMOS IC80LV51/31 is functionally compatible with the industry standard 80C51 microcontrollers.

The IC80LV51/31 is designed with 4K x 8 ROM (IC80LV51 only); 128 x 8 RAM; 32 programmable I/O lines; a serial I/O port for either multiprocessor communications, I/O expansion or full duplex UART; two 16-bit timer/counters; a six-source, two-priority-level, nested interrupt structure; and an on-chip oscillator and clock circuit. The IC80LV51/31 can be expanded using standard TTL compatible memory.

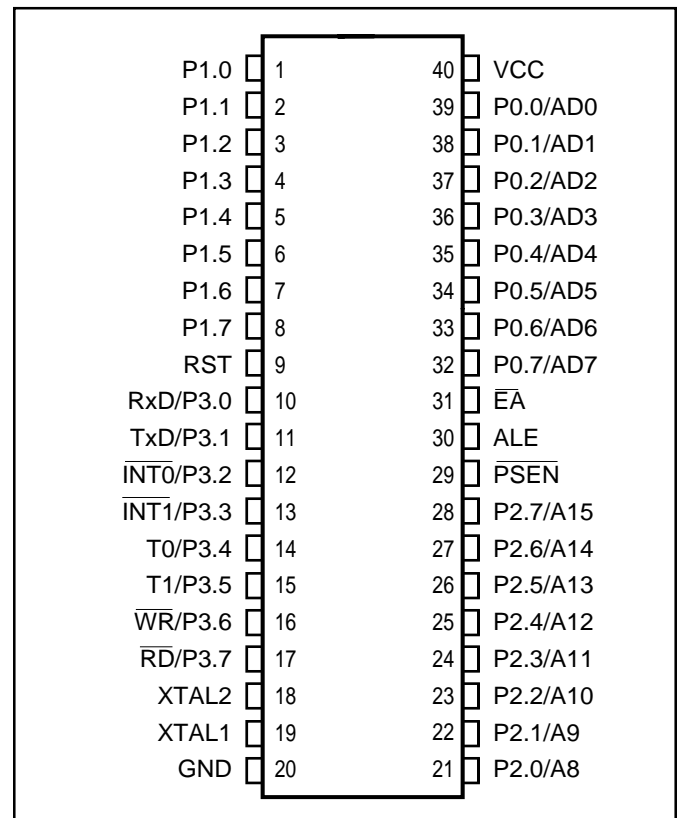


Figure 1. IC80LV51/31 Pin Configuration: 40-pin DIP

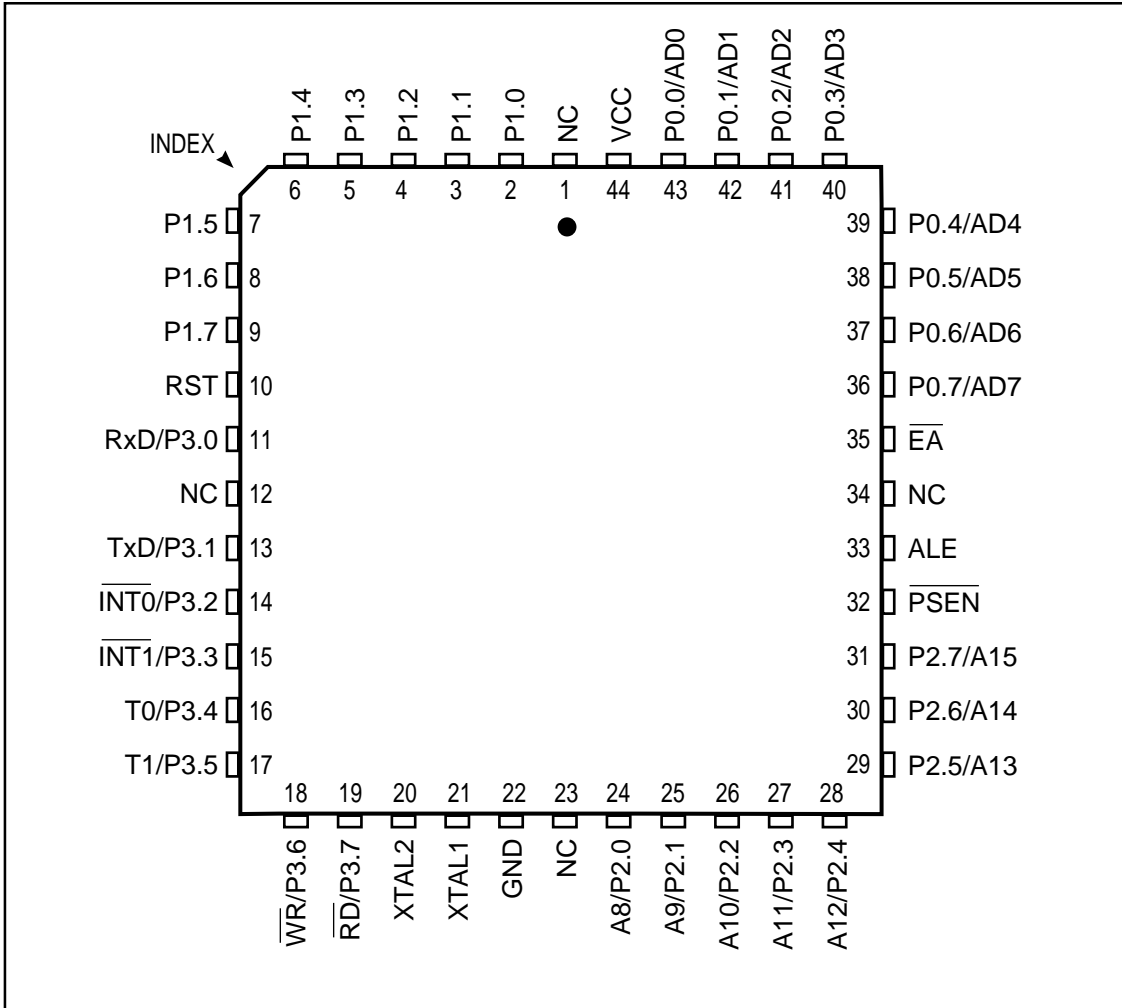


Figure 2. IC80LV51/31 Pin Configuration: 44-pin PLCC

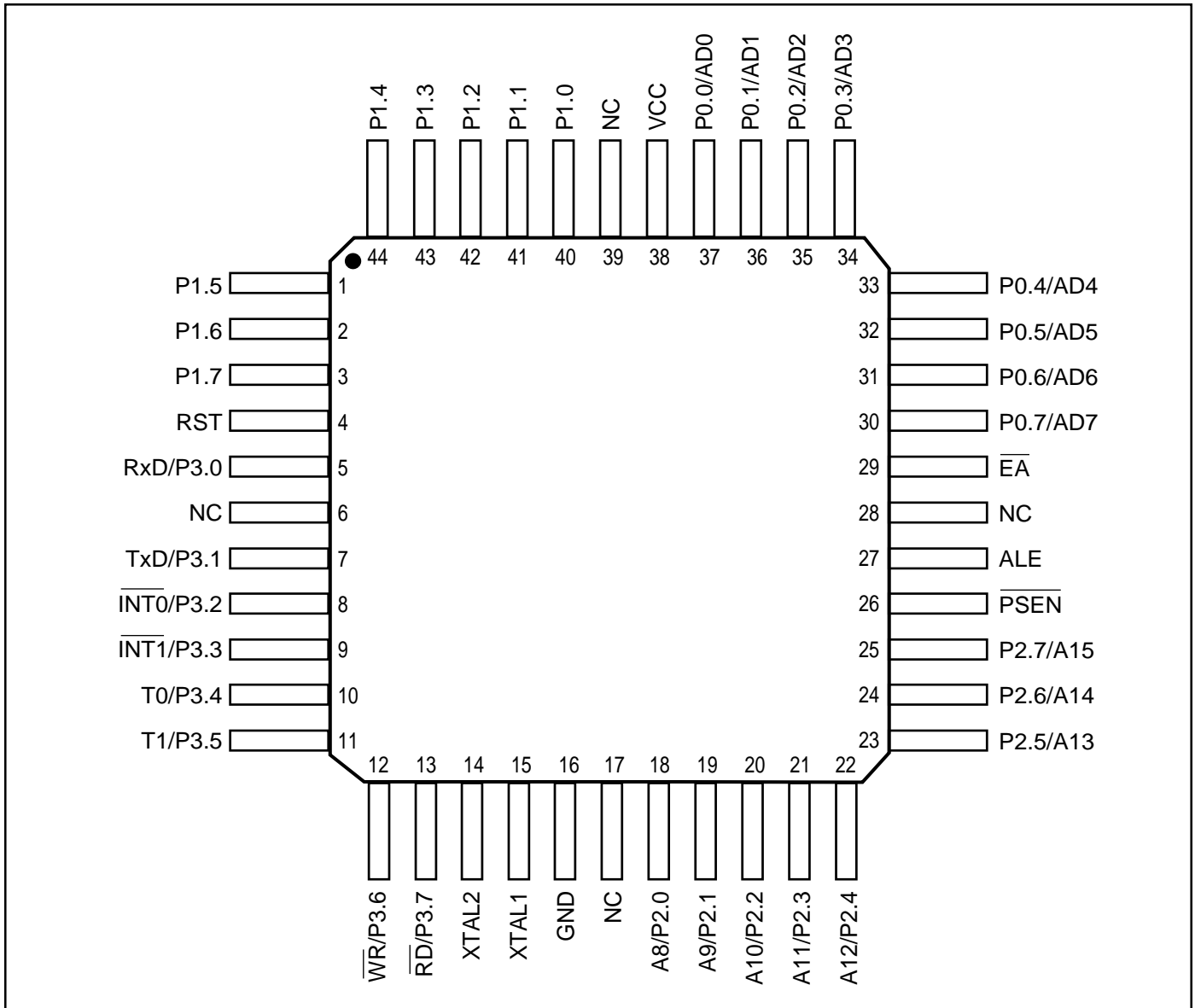


Figure 3. IC80LV51/31 Pin Configuration: 44-pin PQFP

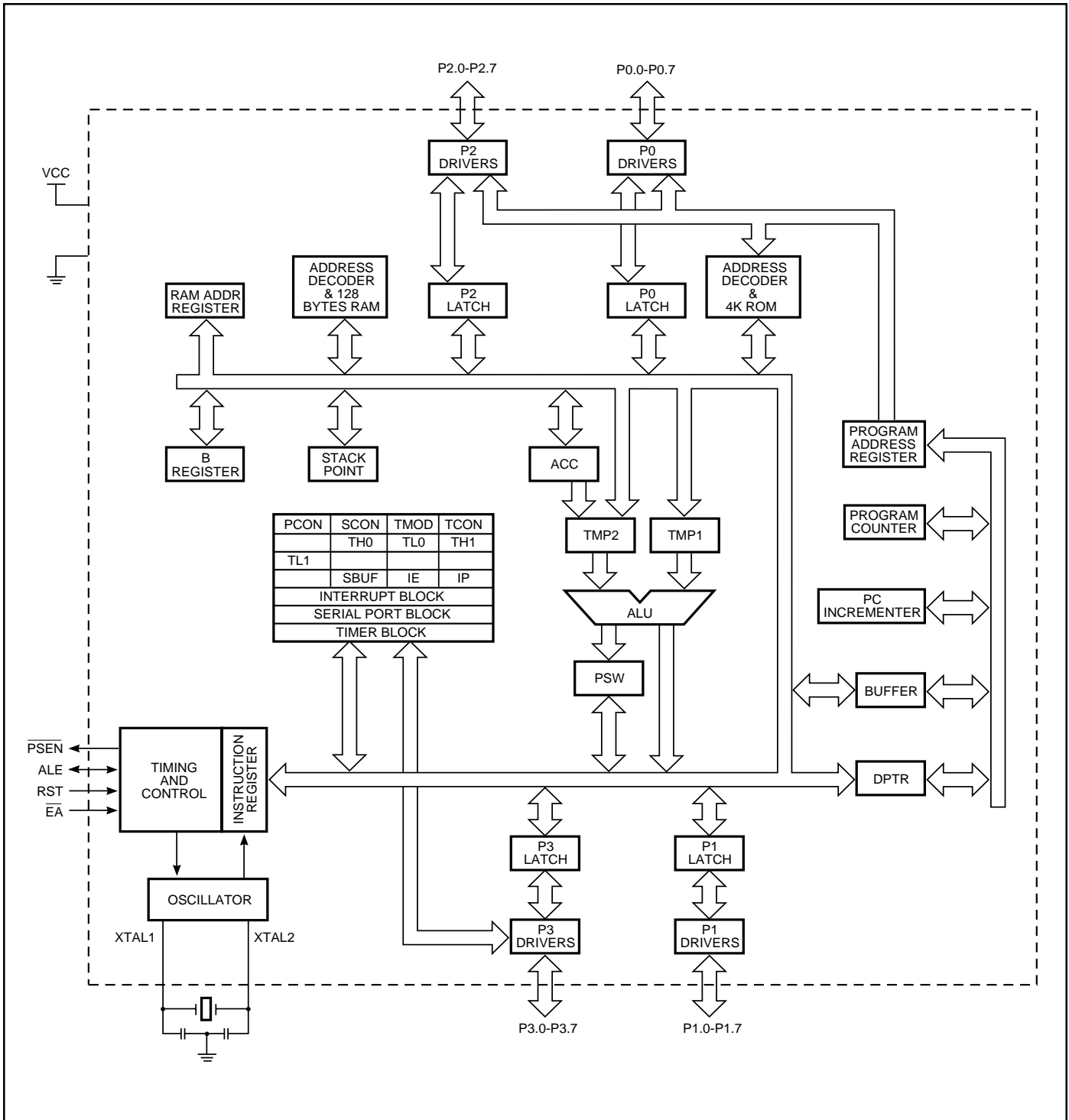


Figure 4. IC80LV51/31 Block Diagram

Table 1. Detailed Pin Description

Symbol	PDIP	PLCC	PQFP	I/O	Name and Function
ALE	30	33	27	I/O	<b>Address Latch Enable:</b> Output pulse for latching the low byte of the address during an address to the external memory. In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory.
$\overline{EA}$	31	35	29	I	<b>External Access enable:</b> $\overline{EA}$ must be externally held low to enable the device to fetch code from external program memory locations 0000H to FFFFH. If $\overline{EA}$ is held high, the device executes from internal program memory unless the program counter contains an address greater than 0FFFH.
P0.0-P0.7	39-32	43-36	37-30	I/O	<b>Port 0:</b> Port 0 is an 8-bit open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program and data memory. In this application, it uses strong internal pullups when emitting 1s.
P1.0-P1.7	1-8	2-9	40-44 1-3	I/O	<b>Port 1:</b> Port 1 is an 8-bit bidirectional I/O port with internal pullups. Port 1 pins that have 1s written to them are pulled high by the internal pullups and can be used as inputs. As inputs, Port 1 pins that are externally pulled low will source current because of the internal pullups. (See DC Characteristics: $I_{IL}$ ). The Port 1 output buffers can sink/source four TTL inputs.  Port 1 also receives the low-order address byte during ROM verification.
P2.0-P2.7	21-28	24-31	18-25	I/O	<b>Port 2:</b> Port 2 is an 8-bit bidirectional I/O port with internal pullups. Port 2 pins that have 1s written to them are pulled high by the internal pullups and can be used as inputs. As inputs, Port 2 pins that are externally pulled low will source current because of the internal pullups. (See DC Characteristics: $I_{IL}$ ). Port 2 emits the high order address byte during fetches from external program memory and during accesses to external data memory that used 16-bit addresses (MOVX @ DPTR). In this application, Port 2 uses strong internal pullups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @ Ri [i = 0, 1]), Port 2 emits the contents of the P2 Special Function Register.  Port 2 also receives the high-order bits and some control signals during ROM verification.

Table 1. Detailed Pin Description (continued)

Symbol	PDIP	PLCC	PQFP	I/O	Name and Function
P3.0-P3.7	10-17	11, 13-19	5, 7-13	I/O	<p><b>Port 3:</b> Port 3 is an 8-bit bidirectional I/O port with internal pullups. Port 3 pins that have 1s written to them are pulled high by the internal pullups and can be used as inputs. As inputs, Port 3 pins that are externally pulled low will source current because of the internal pullups. (See DC Characteristics: I<sub>IL</sub>).</p> <p>Port 3 also serves the special features of the IC80LV51/31, as listed below:</p> <p><b>RxD (P3.0):</b> Serial input port.  <b>TxD (P3.1):</b> Serial output port.  <b>INT0 (P3.2):</b> External interrupt 0.  <b>INT1 (P3.3):</b> External interrupt 1.  <b>T0 (P3.4):</b> Timer 0 external input.  <b>T1 (P3.5):</b> Timer 1 external input.  <b>WR (P3.6):</b> External data memory write strobe.  <b>RD (P3.7):</b> External data memory read strobe.</p>
PSEN	29	32	26	O	<p><b>Program Store Enable:</b> The read strobe to external program memory. When the device is executing code from the external program memory, PSEN is activated twice each machine cycle except that two PSEN activations are skipped during each access to external data memory. PSEN is not activated during fetches from internal program memory.</p>
RST	9	10	4	I	<p><b>Reset:</b> A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal MOS resistor to GND permits a power-on reset using only an external capacitor connected to Vcc.</p>
XTAL 1	19	21	15	I	<p><b>Crystal 1:</b> Input to the inverting oscillator amplifier and input to the internal clock generator circuits.</p>
XTAL 2	18	20	14	O	<p><b>Crystal 2:</b> Output from the inverting oscillator amplifier.</p>
GND	20	22	16	I	<p><b>Ground:</b> 0V reference.</p>
Vcc	40	44	38	I	<p><b>Power Supply:</b> This is the power supply voltage for operation.</p>

## OPERATING DESCRIPTION

The detail description of the IC80LV51/31 included in this description are:

- Memory Map and Registers
- Timer/Counters
- Serial Interface
- Interrupt System
- Other Information

The detail information description of the IC80LV51/31 refer to IC80C51/31 date sheet

## OTHER INFORMATION

### Reset

The reset input is the RST pin, which is the input to a Schmitt Trigger.

A reset is accomplished by holding the RST pin high for at least two machine cycles (24 oscillator periods), *while the oscillator is running*. The CPU responds by generating an internal reset, with the timing shown in Figure 6.

The external reset signal is asynchronous to the internal clock. The RST pin is sampled during State 5 Phase 2 of every machine cycle. The port pins will maintain their current activities for 19 oscillator periods after a logic 1 has been sampled at the RST pin; that is, for 19 to 31 oscillator periods after the external reset signal has been applied to the RST pin.

The internal reset algorithm writes 0s to all the SFRs except the port latches, the Stack Pointer, and SBUF. The port latches are initialized to FFH, the Stack Pointer to 07H, and SBUF is indeterminate. Table 2 lists the SFRs and their reset values.

Then internal RAM is not affected by reset. On power-up the RAM content is indeterminate.

Table 2. Reset Values of the SFR's

SFR Name	Reset Value
PC	0000H
ACC	00H
B	00H
PSW	00H
SP	07H
DPTR	0000H
P0–P3	FFH
IP	XXX00000B
IE	0XX00000B
TMOD	00H
TCON	00H
TH0	00H
TL0	00H
TH1	00H
TL1	00H
SCON	00H
SBUF	Indeterminate
PCON	0XXX0000B

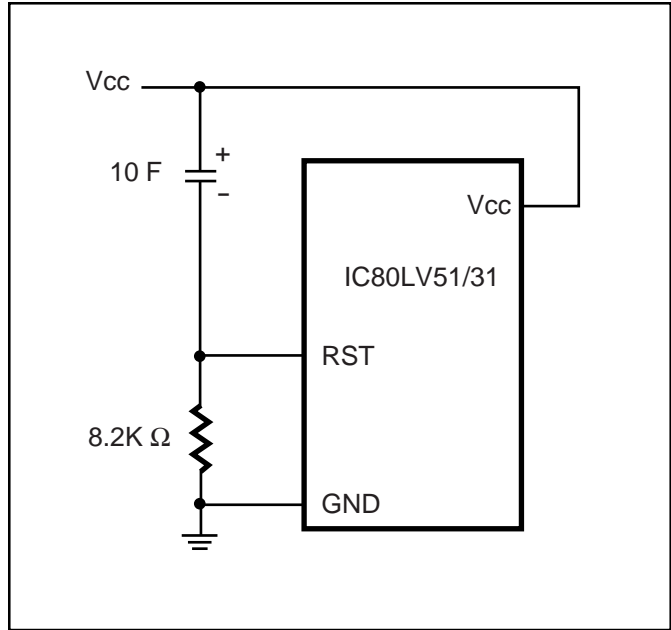
**Power-on Reset**

An automatic reset can be obtained when Vcc goes through a 10µF capacitor and GND through an 8.2K resistor (see Figure 5), providing the Vcc rise time does not exceed 1 msec and the oscillator start-up time does not exceed 10 msec. For the IC80LV51/31, the external resistor can be removed because the RST pin has an internal pulldown. The capacitor value can then be reduced to 1 µF

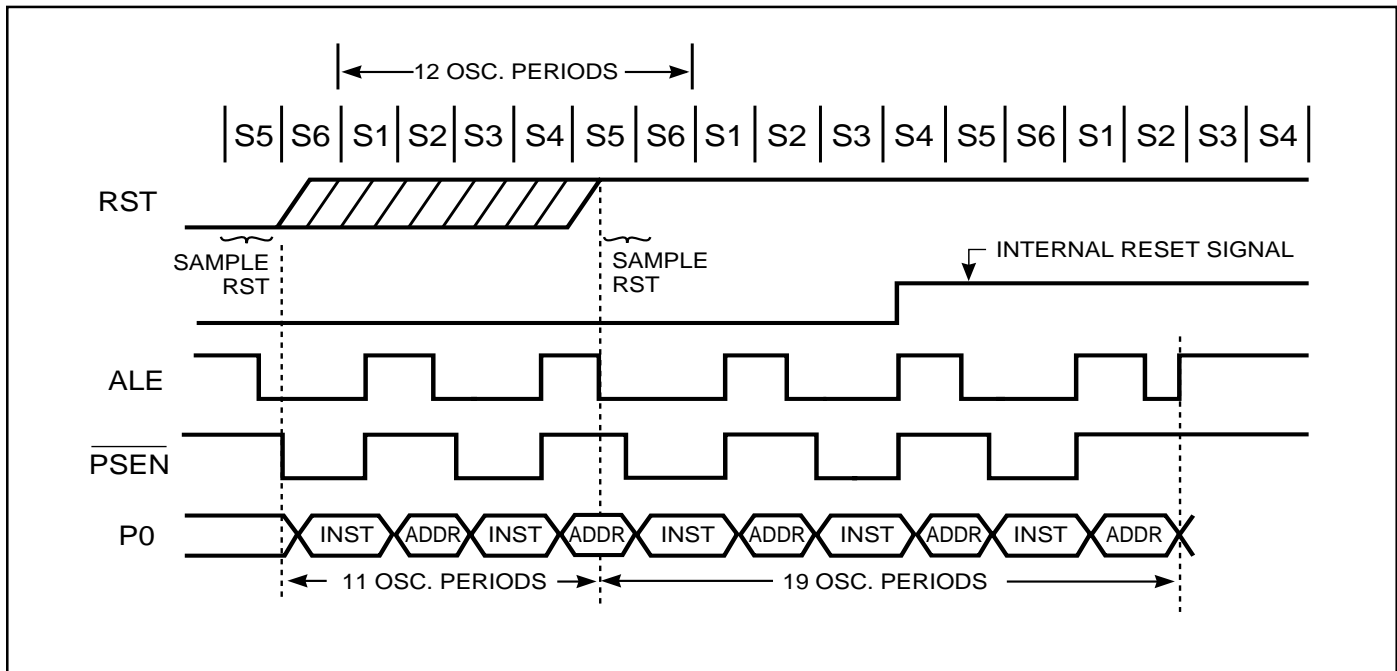
When power is turned on, the circuit holds the RST pin high for an amount of time that depends on the value of the capacitor and the rate at which it charges. To ensure a good reset, the RST pin must be high long enough to allow the oscillator time to start-up (normally a few msec) plus two machine cycles.

*Note that the port pins will be in a random state until the oscillator has start and the internal reset algorithm has written 1s to them.*

With this circuit, reducing Vcc quickly to 0 causes the RST pin voltage to momentarily fall below 0V. However, this voltage is internally limited, and will not harm the device.



**Figure 5. Power-On Reset Circuit**



**Figure 6. Reset Timing**



## Power-Saving Modes of Operation

The IC80LV51/31 has two power-reducing modes. Idle and Power-down. The input through which backup power is supplied during these operations is  $V_{cc}$ . Figure 7 shows the internal circuitry which implements these features. In the Idle mode ( $IDL = 1$ ), the oscillator continues to run and the Interrupt, Serial Port, and Timer blocks continue to be clocked, but the clock signal is gated off to the CPU. In Power-down ( $PD = 1$ ), the oscillator is frozen. The Idle and Power-down modes are activated by setting bits in Special Function Register PCON.

### Idle Mode

An instruction that sets PCON.0 is the last instruction executed before the Idle mode begins. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the Interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirety: the Stack Pointer, Program Counter, Program Status Word, Accumulator, and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated. ALE and PSEN hold at logic high levels.

There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into Idle.

The flag bits GF0 and GF1 can be used to indicate whether an interrupt occurred during normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.

The other way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset must be held active for only two machine cycles (24 oscillator periods) to complete the reset.

The signal at the RST pin clears the IDL bit directly and asynchronously. At this time, the CPU resumes program execution from where it left off; that is, at the instruction following the one that invoked the Idle Mode. As shown in Figure 19, two or three machine cycles of program execution may take place before the internal reset algorithm takes control. On-chip hardware inhibits access to the internal RAM during his time, but access to the port pins is not inhibited. To eliminate the possibility of unexpected outputs at the port pins, the instruction following the one that invokes Idle should not write to a port pin or to external data RAM.

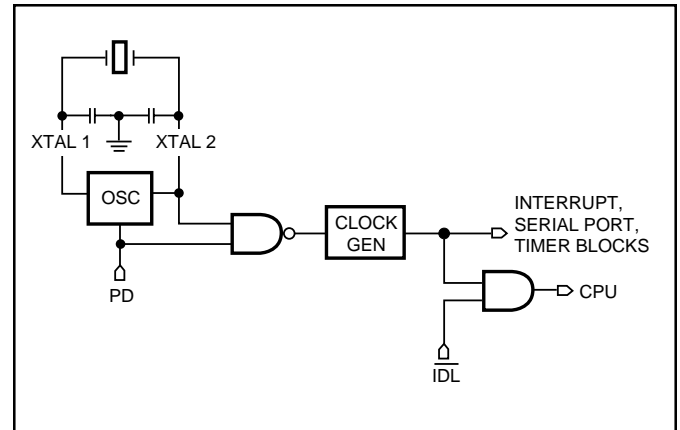


Figure 7. Idle and Power-Down Hardware

### Power-down Mode

An instruction that sets PCON.1 is the last instruction executed before Power-down mode begins. In the Power-down mode, the on-chip oscillator stops. With the clock frozen, all functions are stopped, but the on-chip RAM and Special function Registers are held. The port pins output the values held by their respective SFRs. ALE and PSEN output lows.

In the Power-down mode of operation,  $V_{cc}$  can be reduced to as low as 2V. However,  $V_{cc}$  must not be reduced before the Power-down mode is invoked, and  $V_{cc}$  must be restored to its normal operating level before the Power-down mode is terminated. The reset that terminates Power-down also frees the oscillator. The reset should not be activated before  $V_{cc}$  is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize (normally less than 10 msec).

The only exit from Power-down is a hardware reset. Reset redefines all the SFRs but does not change the on-chip RAM.

Table 3. Status of the External Pins During Idle and Power-down Modes.

Mode	Memory	ALE	$\overline{\text{PSEN}}$	PORT 0	PORT 1	PORT 2	PORT 3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

### On-Chip Oscillators

The on-chip oscillator circuitry of the IC80LV51/31 is a single stage linear inverter, intended for use as a crystal-controlled, positive reactance oscillator (Figure 8). In this application the crystal is operated in its fundamental response mode as an inductive reactance in parallel resonance with capacitance external to the crystal (Figure 8). Examples of how to drive the clock with external oscillator are shown in Figure 9.

The crystal specifications and capacitance values (C1 and C2 in Figure 8) are not critical. 20 pF to 30 pF can be used in these positions at a 12 MHz to 24 MHz frequency with good quality crystals. A ceramic resonator can be used in place of the crystal in cost-sensitive applications. When a ceramic resonator is used, C1 and C2 are normally selected to be of somewhat higher values. The manufacturer of the ceramic resonator should be consulted for recommendation on the values of these capacitors.

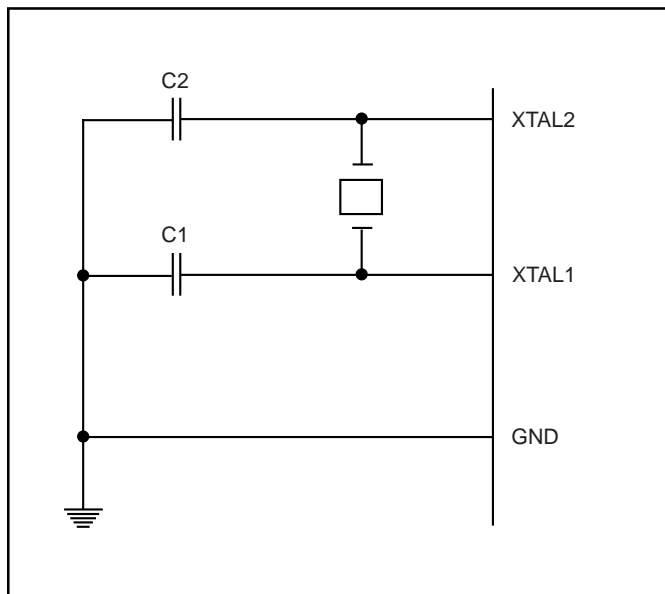


Figure 8. Oscillator Connections

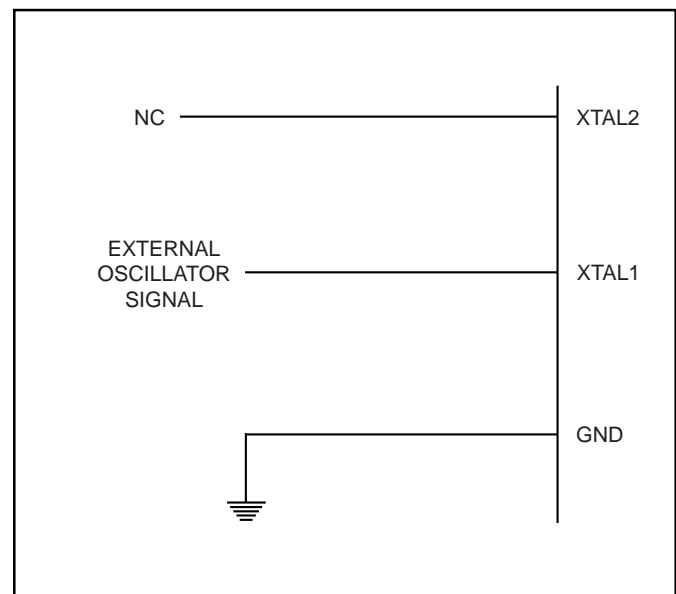


Figure 9. External Clock Drive Configuration

Table 4. Recommended Value for C1, C2, R

Frequency Range 4 MHz - 24 MHz	
C1	20 pF-30 pF
C2	20 pF-30 pF
R	Not Apply

## ROM Verification

The on-chip memory can be read out for ROM verification. The address of the program memory location to be read is applied to Port 1 and pins P2.3-P2.0. The other pins should be held at the "Verify" level. The contents of the addressed locations will be emitted on Port 0. External pullups are required on Port 0 for this operation. Figure 10 shows the setup to verify the program memory.

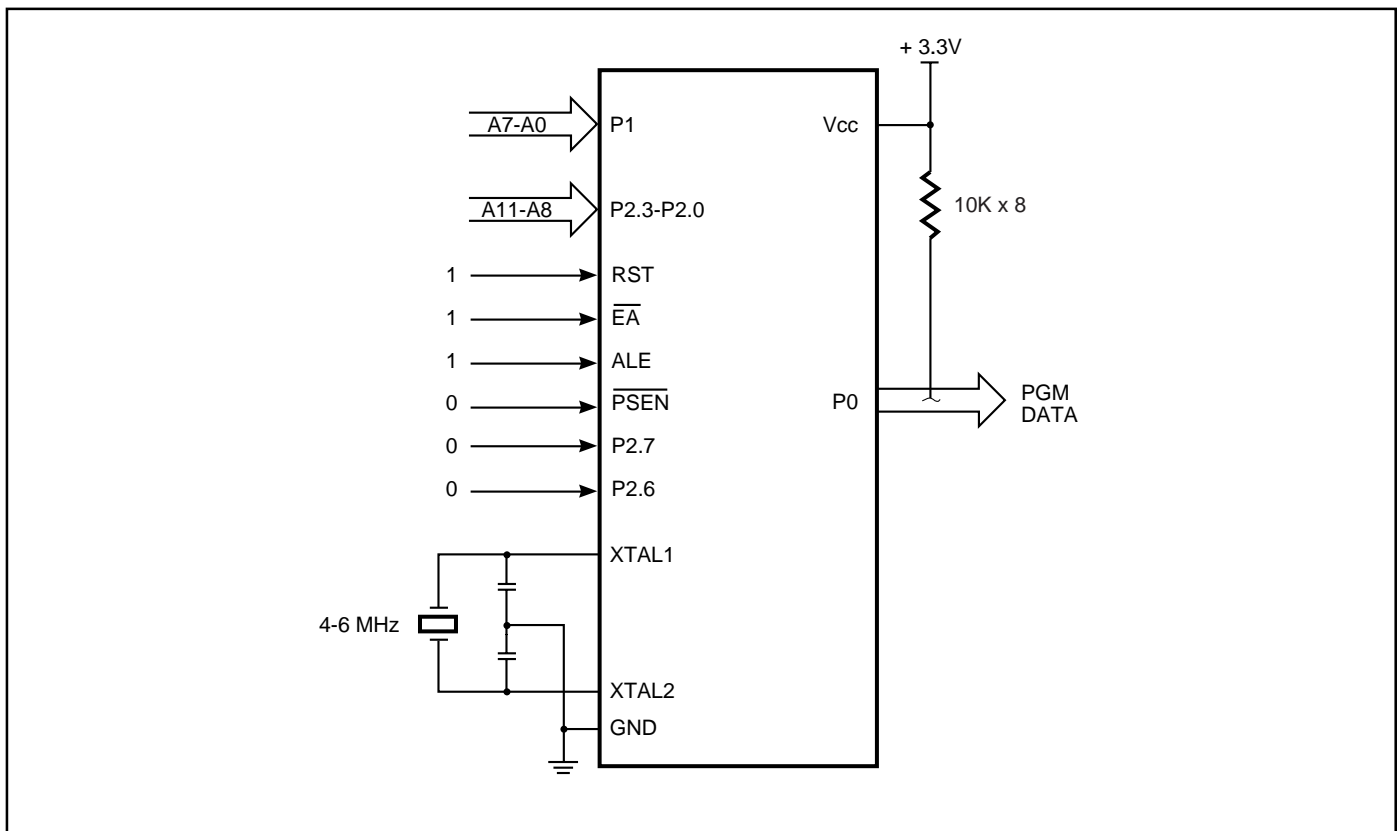


Figure 10. ROM Verification

## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

Symbol	Parameter	Value	Unit
V <sub>TERM</sub>	Terminal Voltage with Respect to GND <sup>(2)</sup>	-2.0 to +7.0	V
T <sub>BIAS</sub>	Temperature Under Bias <sup>(3)</sup>	0 to +70	°C
T <sub>STG</sub>	Storage Temperature	-65 to +125	°C
P <sub>T</sub>	Power Dissipation	1.5	W

**Note:**

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. Minimum DC input voltage is -0.5V. During transitions, inputs may undershoot to -2.0V for periods less than 20 ns. Maximum DC voltage on output pins is V<sub>CC</sub> + 0.5V which may overshoot to V<sub>CC</sub> + 2.0V for periods less than 20 ns.
3. Operating temperature is for commercial products only defined by this specification.

## OPERATING RANGE<sup>(1)</sup>

Range	Ambient Temperature	V <sub>CC</sub>	Oscillator Frequency
Commercial	0°C to +70°C	3.3V ± 10%	3.5 to 24 MHz

**Note:**

1. Operating ranges define those limits between which the functionality of the device is guaranteed.

## DC CHARACTERISTICS

( $T_A = 0^\circ\text{C}$  to  $70^\circ\text{C}$ ;  $V_{CC} = 3.3\text{V} \pm 10\%$ ;  $\text{GND} = 0\text{V}$ )

Symbol	Parameter	Test conditions	Min	Max	Unit
$V_{IL}$	Input low voltage (All except $\overline{EA}$ )		-0.5	$0.2V_{CC} + 0.1$	V
$V_{IL1}$	Input low voltage ( $\overline{EA}$ )		-0.5	$0.2V_{CC} + 0.1$	V
$V_{IH}$	Input high voltage (All except XTAL 1, RST)		$0.2V_{CC} + 0.9$	$V_{CC} + 0.5$	V
$V_{IH1}$	Input high voltage (XTAL 1)		$0.7V_{CC}$	$V_{CC} + 0.5$	V
$V_{SCH+}$	RST positive schmitt-trigger threshold voltage		$0.7V_{CC}$	$V_{CC} + 0.5$	V
$V_{SCH-}$	RST negative schmitt-trigger threshold voltage		0	$0.3V_{CC}$	V
$V_{OL}^{(1)}$	Output low voltage (Ports 1, 2, 3)	$I_{OL} = 1.6 \text{ mA}$	—	0.45	V
$V_{OL1}^{(1)}$	Output low voltage (Port 0, ALE, $\overline{PSEN}$ )	$I_{OL} = 3.2 \text{ mA}$	—	0.45	V
$V_{OH}$	Output high voltage (Ports 1, 2, 3, ALE, $\overline{PSEN}$ )	$I_{OH} = -20 \mu\text{A}$	$V_{CC} - 0.9$	—	V
$V_{OH1}$	Output high voltage (Port 0, ALE, $\overline{PSEN}$ )	$I_{OH} = -800 \mu\text{A}$	$V_{CC} - 0.9$	—	V
$I_{IL}$	Logical 0 input current (Ports 1, 2, 3)	$V_{IN} = 0.45\text{V}$	—	-50	$\mu\text{A}$
$I_{LI}$	Input leakage current (Port 0)	$0.45\text{V} < V_{IN} < V_{CC}$	-5	+5	$\mu\text{A}$
$I_{TL}$	Logical 1-to-0 transition current (Ports 1, 2, 3)	$V_{IN} = 2.0\text{V}$	—	-450	$\mu\text{A}$
$R_{RST}$	RST pulldown resistor		150	450	$\text{K}\Omega$

### Note:

1. Under steady state (non-transient) conditions,  $I_{OL}$  must be externally limited as follows:

Maximum  $I_{OL}$  per port pin: 10 mA

Maximum  $I_{OL}$  per 8-bit port

Port 0: 26 mA

Ports 1, 2, 3: 15 mA

Maximum total  $I_{OL}$  for all output pins: 71 mA

If  $I_{OL}$  exceeds the test condition,  $V_{OL}$  may exceed the related specification.

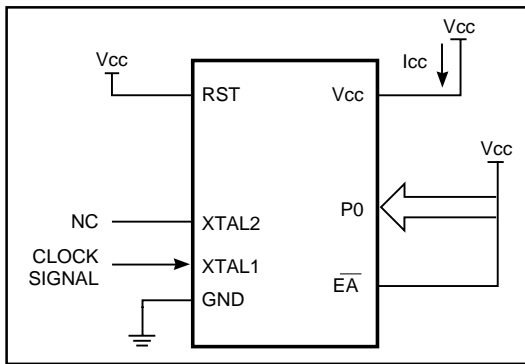
Pins are not guaranteed to sink greater than the listed test conditions.

**POWER SUPPLY CHARACTERISTICS**

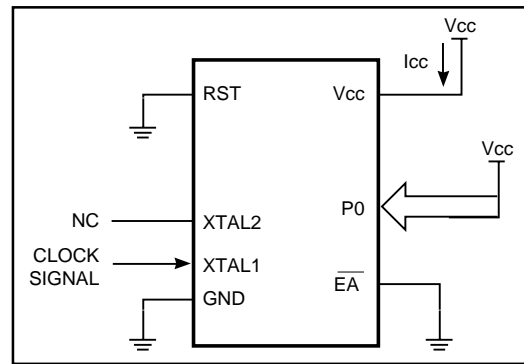
Symbol	Parameter	Test conditions	Min	Max	Unit
I <sub>cc</sub>	Power supply current <sup>(1)</sup>	V <sub>cc</sub> = 3.3V			
	Active mode	12 MHz	—	15	mA
		24 MHz	—	24	mA
	Idle mode	12 MHz	—	4	mA
		24 MHz	—	8	mA
	Power-down mode	V <sub>cc</sub> = 3.3V	—	50	μA

**Note:**

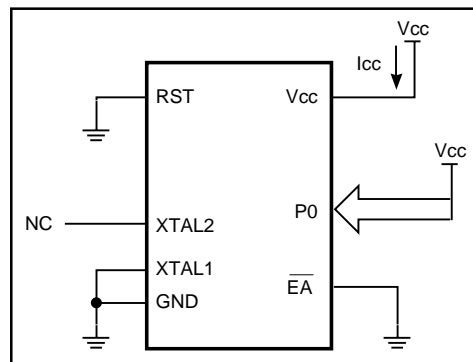
1. See Figures 11, 12, 13, and 14 for I<sub>cc</sub> test conditions.



**Figure 11. Active Mode**



**Figure 12. Idle Mode**



**Figure 13. Power-down Mode**

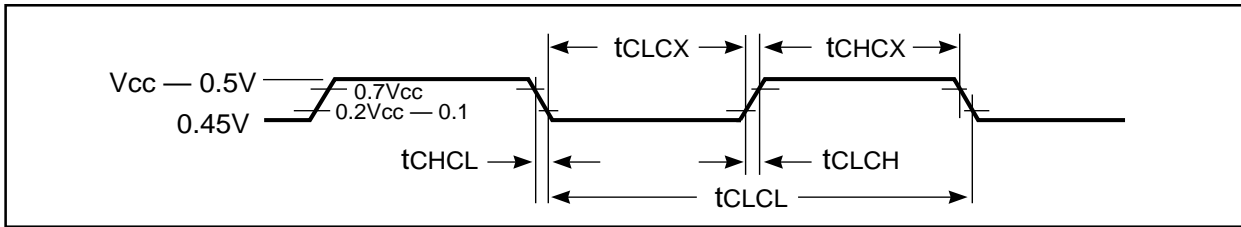


Figure 14. Clock Signal Waveform for  $I_{cc}$  Tests in Active and Idle Modes. ( $t_{CLCH} = t_{CHCL} = 5$  ns)

## AC CHARACTERISTICS

( $T_A = 0^\circ\text{C}$  to  $70^\circ\text{C}$ ;  $V_{CC} = 3.3\text{V} \pm 10\%$ ;  $GND = 0\text{V}$ ; CI for Port 0, ALE and  $\overline{\text{PSEN}}$  Outputs = 100 pF; CI for other outputs = 80 pF)

## EXTERNAL MEMORY CHARACTERISTICS

Symbol	Parameter	12 MHz Clock		24 MHz Clock		Variable Oscillator (3.5-24 MHz)		Unit
		Min	Max	Min	Max	Min	Max	
1/tCLCL	Oscillator frequency	—	—	—	—	3.5	24	MHz
tLHLL	ALE pulse width	152	—	68	—	$2t_{CLCL}-15$	—	ns
tAVLL	Address valid to ALE low	68	—	26	—	$t_{CLCL}-15$	—	ns
tLLAX	Address hold after ALE low	73	—	31	—	$t_{CLCL}-10$	—	ns
tLLIV	ALE low to valid instr in	—	313	—	147	—	$4t_{CLCL}-20$	ns
tLLPL	ALE low to $\overline{\text{PSEN}}$ low	73	—	31	—	$t_{CLCL}-10$	—	ns
tPLPH	$\overline{\text{PSEN}}$ pulse width	235	—	110	—	$3t_{CLCL}-15$	—	ns
tPLIV	$\overline{\text{PSEN}}$ low to valid instr in	—	230	—	105	—	$3t_{CLCL}-20$	ns
tPXIX	Input instr hold after $\overline{\text{PSEN}}$	0	—	0	—	0	—	ns
tPXIZ	Input instr float after $\overline{\text{PSEN}}$	—	78	—	37	—	$t_{CLCL}-5$	ns
tAVIV	Address to valid instr in	—	397	—	188	—	$5t_{CLCL}-20$	ns
tPLAZ	$\overline{\text{PSEN}}$ low to address float	—	10	—	10	—	10	ns
tRLRH	$\overline{\text{RD}}$ pulse width	480	—	230	—	$6t_{CLCL}-20$	—	ns
tWLWH	$\overline{\text{WR}}$ pulse width	480	—	230	—	$6t_{CLCL}-20$	—	ns
tRLDV	$\overline{\text{RD}}$ low to valid data in	—	323	—	157	—	$4t_{CLCL}-10$	ns
tRHDX	Data hold after $\overline{\text{RD}}$	0	—	0	—	0	—	ns
tRHDZ	Data float after $\overline{\text{RD}}$	—	162	—	78	—	$2t_{CLCL}-5$	ns
tLLDV	ALE low to valid data in	—	573	—	282	—	$7t_{CLCL}-10$	ns
tAVDV	Address to valid data in	—	656	—	323	—	$8t_{CLCL}-10$	ns
tLLWL	ALE low to $\overline{\text{RD}}$ or $\overline{\text{WR}}$ low	230	270	105	145	$3t_{CLCL}-20$	$3t_{CLCL}+20$	ns
tAVWL	Address to $\overline{\text{RD}}$ or $\overline{\text{WR}}$ low	313	—	146	—	$4t_{CLCL}-20$	—	ns
tQVWX	Data valid to $\overline{\text{WR}}$ transition	68	—	26	—	$t_{CLCL}-15$	—	ns
tWHQX	Data hold after $\overline{\text{WR}}$	73	—	31	—	$t_{CLCL}-10$	—	ns
tRLAZ	$\overline{\text{RD}}$ low to address float	—	0	—	0	—	0	ns
tWHLH	$\overline{\text{RD}}$ or $\overline{\text{WR}}$ high to ALE high	68	98	26	57	$t_{CLCL}-15$	$t_{CLCL}+15$	ns

## EXTERNAL MEMORY CHARACTERISTICS *(Continued)*

Symbol	Parameter	12 MHz Clock		24 MHz Clock		Variable Oscillator (3.5-24 MHz)		Unit
		Min	Max	Min	Max	Min	Max	
t <sub>XLXL</sub>	Serial port clock cycle time	990	1010	290	310	12t <sub>CLCL</sub> -10	12t <sub>CLCL</sub> +10	ns
t <sub>QVXH</sub>	Output data setup to clock rising edge	823	—	240	—	10t <sub>CLCL</sub> -10	—	ns
t <sub>XHQX</sub>	Output data hold after clock rising edge	157	—	40	—	2t <sub>CLCL</sub> -10	—	ns
t <sub>XHDX</sub>	Input data hold after clock rising edge	0	—	0	—	0	—	ns
t <sub>XHDV</sub>	Clock rising edge to input data valid	—	833	—	250	—	10t <sub>CLCL</sub>	ns

## EXTERNAL CLOCK DRIVE

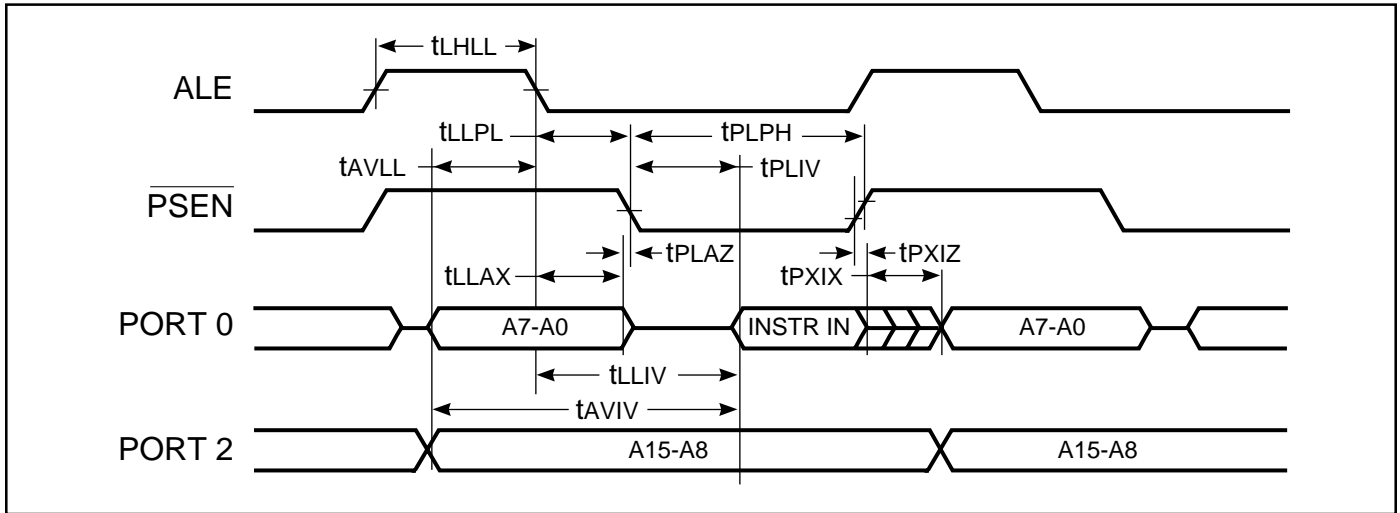
Symbol	wParameter	Min	Max	Unit
1/t <sub>CLCL</sub>	Oscillator Frequency	3.5	40	MHz
t <sub>CHCX</sub>	High time	10	—	ns
t <sub>CLCX</sub>	Low time	10	—	ns
t <sub>CLCH</sub>	Rise time	—	10	ns
t <sub>CHCL</sub>	Fall time	—	10	ns

## ROM VERIFICATION CHARACTERISTICS

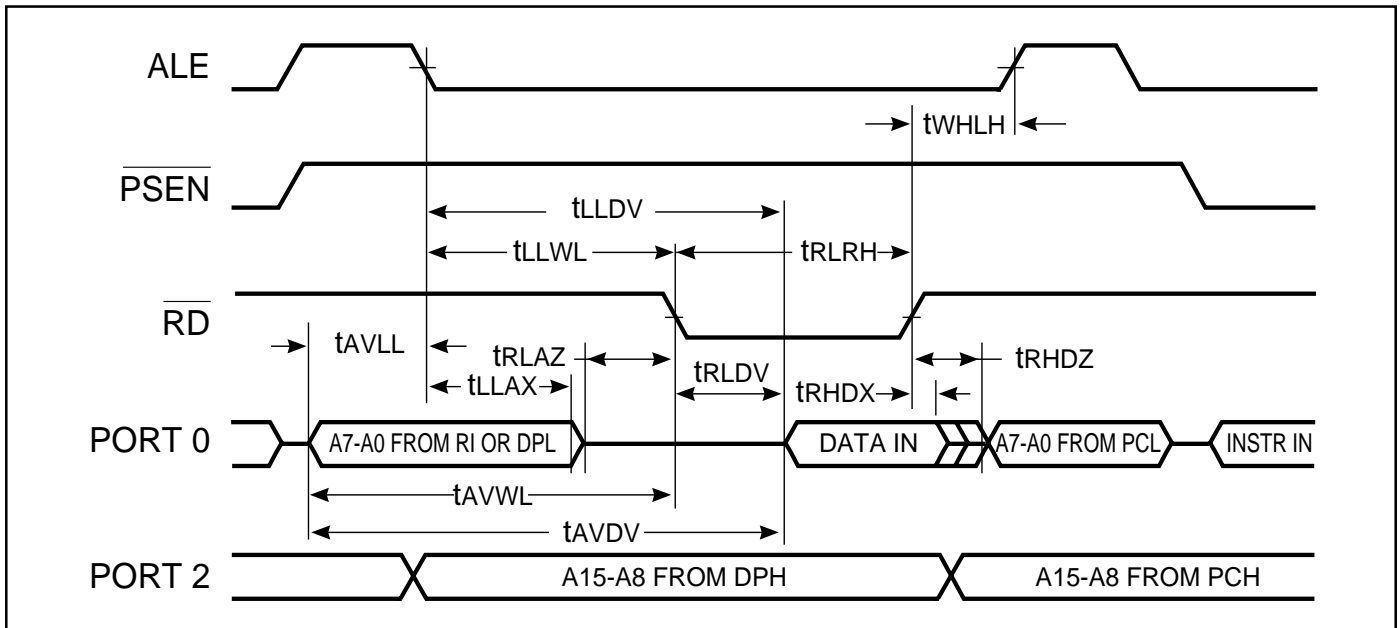
Symbol	Parameter	Min	Max	Unit
1/t <sub>CLCL</sub>	Oscillator Frequency	4	6	MHz
t <sub>AVQV</sub>	Address to data valid	—	48t <sub>CLCL</sub>	
t <sub>ELQV</sub>	ENABLE low to data valid	—	48t <sub>CLCL</sub>	
t <sub>EHQZ</sub>	Data float after ENABLE	0	48t <sub>CLCL</sub>	



**TIMING WAVEFORMS**



**Figure 15. External Program Memory Read Cycle**



**Figure 16. External Data Memory Read Cycle**

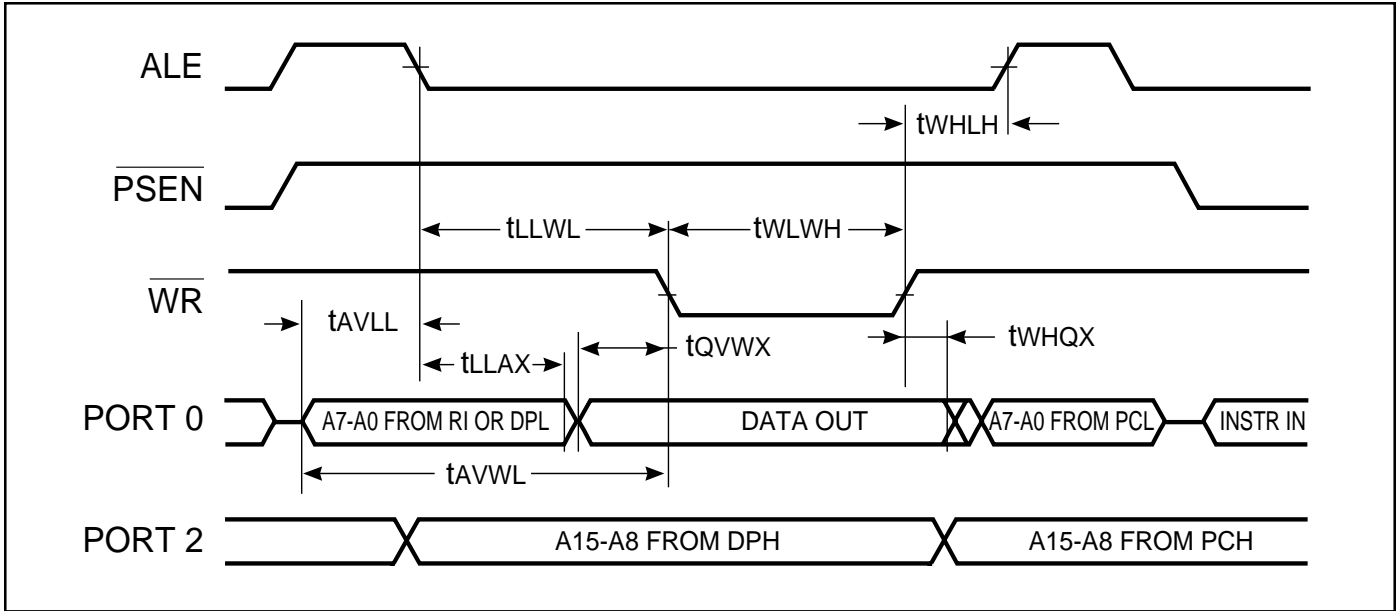


Figure 17. External Data Memory Write Cycle

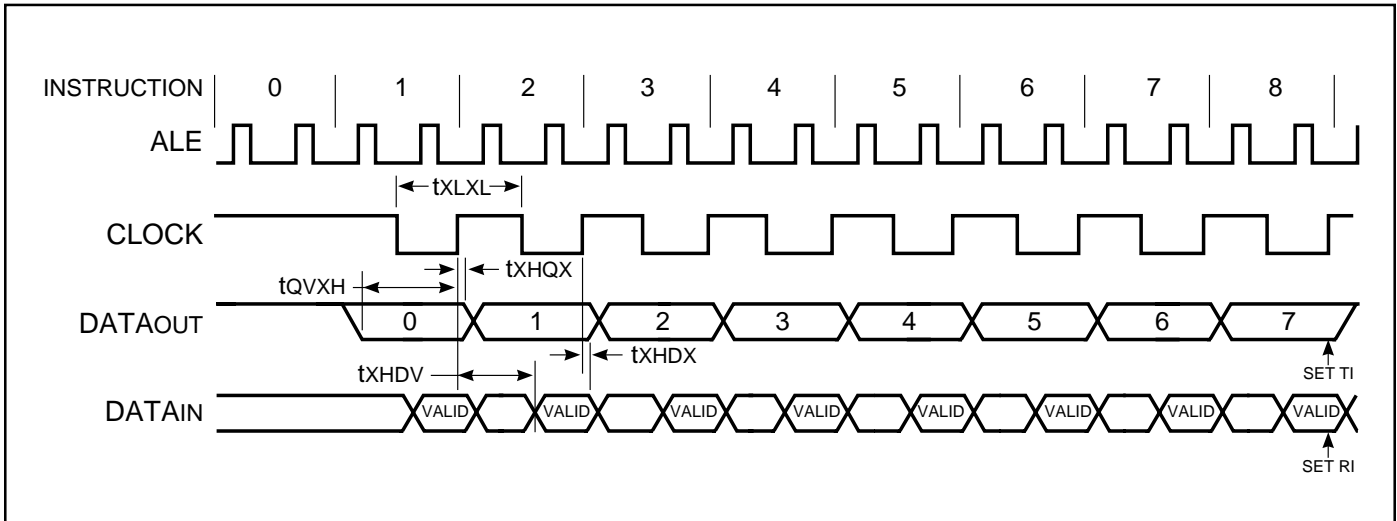


Figure 18. Shift Register Mode Timing Waveform

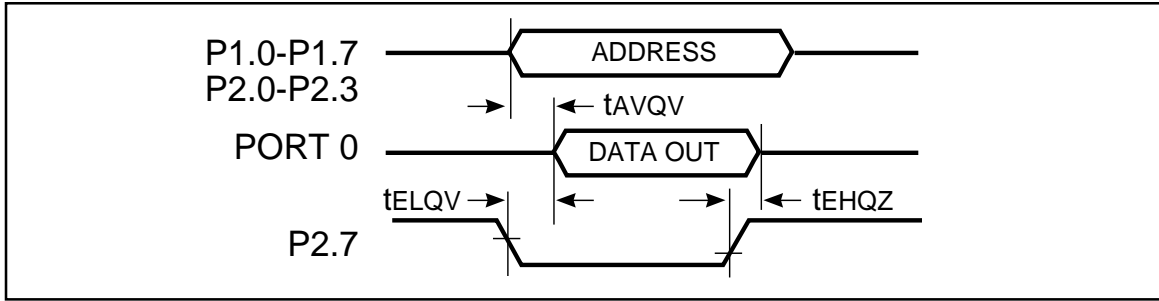


Figure 19. ROM Verification Waveform

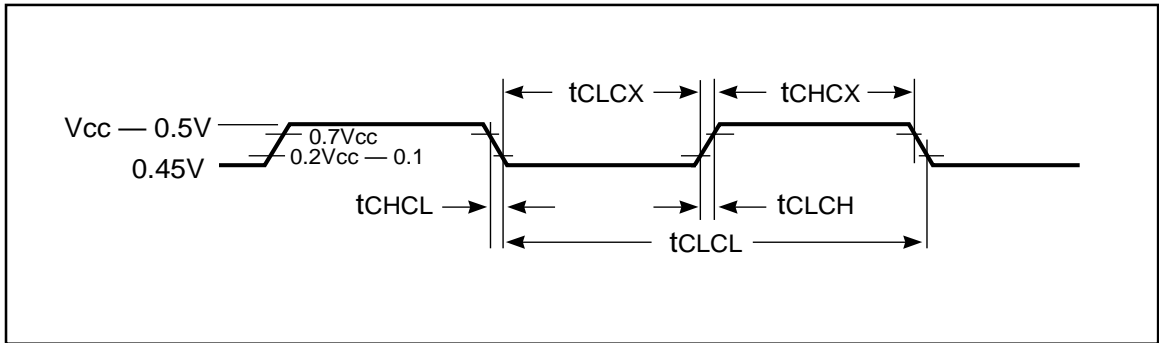


Figure 20. External Clock Drive Waveform

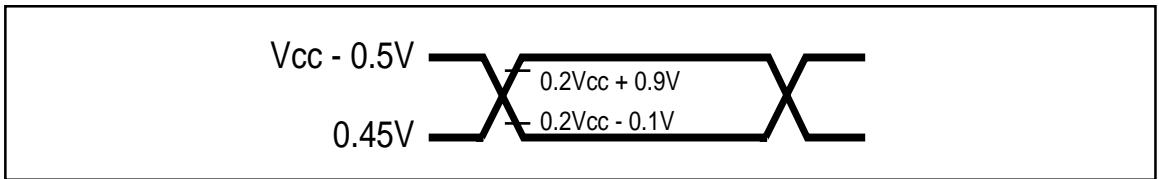


Figure 21. AC Test Point

**Note:**

1. AC inputs during testing are driven at  $V_{CC} - 0.5V$  for logic "1" and  $0.45V$  for logic "0". Timing measurements are made at  $V_{IH}$  min for logic "1" and max for logic "0".

**ORDERING INFORMATION**

**COMMERCIAL TEMPERATURE: 0°C to +70°C**

Speed	Order Part Number	Package
24 MHz	IC80LV51-24PL	PLCC
	IC80LV51-24PQ	PQFP
	IC80LV51-24W	600mil DIP
24 MHz	IC80LV31-24PL	PLCC
	IC80LV31-24PQ	PQFP
	IC80LV31-24W	600mil DIP



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